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(71) Applicant (for all designated States except US): MULTICORE SOLDERS LIMITED [GB/GB]; Kelsey House, Wood Lane End, Hemel Hempstead, Hertfordshire HP2 4RQ (GB).		Published <i>With international search report. Before the expiration of the time limit for amending the claims and to be republished in the event of the receipt of amendments.</i>	
(71)(72) Applicant and Inventor: CRAIG, Hugh, Patrick [US/GB]; 7 Usk Bridge Mews, Usk, Gwent NP15 1SW (GB).			
(72) Inventor; and			
(75) Inventor/Applicant (for US only): LOWRIE, David, John, James [GB/GB]; 4 The Close, Bracebridge Heath, Lincoln ON4 2PB (GB).			
(74) Agent: SILVERMAN, Warren; Haseltine Lake & Co., Imperial House, 15-19 Kingsway, London WC2B 6UD (GB).			
(54) Title: <u>ADHESIVE AND ENCAPSULATING MATERIAL WITH FLUXING PROPERTIES</u>			
(57) Abstract Use is made in attachment of an electrical component to an electrical termination on a component-carrying substrate by a solder bump technique of a thermally curable adhesive composition for encapsulating purposes which comprises a thermosetting polymer and a chemical cross-linking agent which has fluxing properties but which is unreactive or of severely restricted reactivity with the polymer without the action of heat and/or catalyst. The composition is to be thermally curable when heated to soldering temperatures in a reaction which is catalysable merely by metal oxide fluxed from metal surfaces by cross-linking agent then dissolved in the thermosetting polymer.			